



TO-92 物料成分表

Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition	CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English		
Die	1.5	Si	7440-21-3	100.00%
Lead Frame	7.263	Cu	7440-50-8	balance
		Fe	7439-89-6	0.05-0.15
		P	7723-14-0	0.025-0.04
		Pb	7439-92-1	≤0.005%
Epoxy	0.08	Silver	7440-22-4	70- < 90 %
		Epoxy Resin.	9003-36-5	10- < 20 %
		butane	2425-79-8	3- < 10 %
		dapsone	80-08-0	1- < 2.5 %
Wire	0.013	Cu	7440-50-8	99.99%
		Others	—	0.01%
Mold Compound	194.56	Epoxy Resin A	—	1-5%
		Epoxy Resin B	—	1-5%
		Phenol Resin	—	5~10%
		Silica(Amorphous) A	60676-86-0	70-90%
		Silica(Amorphous)B	7631-86-9	5-10%
		Carbon Black	1333-86-4	0.1-1%
Plating	0.12	Sn	7440-31-5	99.99%
Total	203.536			

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied. Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.